

### **X-CON BRAND**

### **CONDUCTIVE POLYMER ALUMINUM SOLID CAPACITORS**

# PRODUCT SPECIFICATION 規格書

CUSTOMER: (客戶):

DATE: (日期):2017-06-14

CATEGORY (品名)	: CONDUCTIVE POLYMER ALUMINUM SOLID CAPACITORS
DESCRIPTION (型号)	: UER 25V220 μ F (φ8X11.5)
VERSION (版本)	: 01
Customer P/N	: /
SUPPLIER	: /

SUPPLIER			CUST	OMER
PREPARED (拟定)	CHECKED (审核)	APPRO (批社		SIGNATURE (签名)
李婷	刘渭清			

		SPECIFICAT	ΓΙΟΝ		ALTERN	ATION HIS	TORY
	UER SERIES			R	ECORDS		
Rev.	Date	Mark	Page	Contents	Purpose	Drafter	Approver

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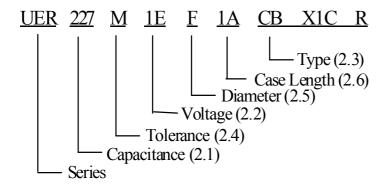
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### 1. Application

This specification applies to conductive polymer aluminum solid capacitors used in electronic equipment.

### 2. Part Number System



#### 2.1 Capacitance code

Code	227
Capacitance (µF)	220

#### 2.2 Rated voltage code

Code	1E
Voltage (W.V.)	25

#### 2.3 <u>Type</u>

Code	СВ
Туре	Forming

2.4 <u>Capacitance tolerance</u> "M" stands for  $-20\% \sim +20\%$ 

#### 2.5 <u>Diameter</u>

Code	F
Diameter	8

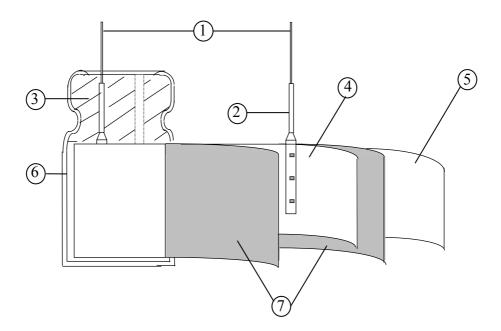
2.6 <u>Case leng</u> 1A=11.5mm

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### **3.**Construction

Single ended type to be produced to fix the terminals to anode and cathode foil, and wind together with paper, and then wound element to be formed and carbonized, impregnated with polymer and polymerized, then will be enclosed in an aluminum case. Finally sealed up tightly with end seal rubber.



No	Component	Material
		Tinned Copper Line
1	Lead Line	or CP Line(Pb Free)
2	Terminal	Aluminum
3	Sealing Material	Rubber
4	Al-Foil (+)	Aluminum
5	Al-Foil (-)	Aluminum
6	Case	Aluminum
7	Electrolyte paper	Manila Hemp

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### 4. Characteristics

#### Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature:15°C to 35°CRelative humidity:45% to75%Air Pressure:86kPa to 106kPa

If there is any doubt about the results, measurement shall be made within the following conditions: Ambient temperature:  $20^{\circ}C \pm 2^{\circ}C$ Relative humidity : 60% to 70%Air Pressure : 86kPa to 106kPa

### Operating temperature range

The ambient temperature range at which the capacitor can be operated continuously at rated voltage is -55°C to 105°C.

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	ITEM			PERFORMANCE						
4.1	Rated voltage (WV) Surge voltage (SV)		WV (V.DC)         25           SV (V.DC)         28.7							
4.2	Nominal capacitance (Tolerance)	Measu Measu Measu <b><crit< b="">e</crit<></b>	<condition>Measuring Frequency: 120Hz<math>\pm</math>12HzMeasuring Voltage: Not more than 0.5VrmsMeasuring Temperature: <math>20\pm 2^{\circ}C</math><criteria>Shall be within the specified capacitance tolerance.</criteria></condition>							
4.3	Leakage current	After $\Omega \pm 1$ when In cas voltag	<b>Condition&gt;</b> After DC Voltage is applied to capacitors through the series protective resistor (1k $\Omega \pm 10 \Omega$ ) so that terminal voltage may reach the rated voltage .The leakage current when measured after 2 minutes shall not exceed the values of the following equation. In case leakage current value exceed the value shown in Table 3, remeasure after voltage treatment that applies the rated voltage shown in 4.1 for 120minutes at 105 °C <b>Criteria&gt;</b> See Table 3							
4.4	tan δ	See 4. <b>Crite</b> Wor		suring frequency, voltage and temperature.						
4.5       ESR <condition> Measuring frequency : 100kHz to 300kHz; Measuring temperature:20±2°C Measuring point :1mm max from the surface of a sealing resin on the lead wire.         4.5       ESR          <criteria> (20°C)Less than the initial limit(See Table 3).</criteria></condition>										
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		STEP	Temperature(°C)	Item	Characteristics	
	1	20±2	Measure: Capacitance tanδ Impedance			
	Turning	2	-55+3	Z-55°C / 20°C	≤1.25	
		3	Keep at 15 to 35°C fo 15 minutes or more			
.6	Temperature characteristic	4	$105 \pm 2$	Z105°C / 20°C	≤1.25	
				∆ C/C 20°C	Within $\pm 5\%$ of step1	
		5	$20\pm 2$	tanδ	Less than or equal to the value of item 4.4	
		The C voltag	dition> apacitor is stored at a te te for 5000 +48/0 hours teria>			
		Item		rformance		
				thin $\pm 20\%$ of initial c	apacitance	
		tan δ	Le	Less than or equal to 1.5 times of the value of item 4.4		
	Load	ESR		Less than or equal to 1.5 times of the value of item 4.5		
.7	life	Leak	-	Less than or equal to the value of item 4.3		
	test	App	earance No	Notable changes shall not be found.		

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4.8	Surge test	Item       Capacitance Change       tan δ	PerformanceWithin $\pm 20\%$ of initial capacitance
4.8	-	tan δ	Within $\pm 20\%$ of initial capacitance
	usi	-	
			Less than or equal to 1.5 times of the value of item 4.4
		ESR	Less than or equal to 1.5 times of the value of item 4.5
		Leakage current	Less than or equal to the value of item 4.3
		<pre>/// // // // // // // // // // // // //</pre>	nulates over voltage at abnormal situation, and not be oltage is always applied.
		60±2°C, the character <b>Criteria&gt;</b> Item Capacitance Change	<ul> <li>xposed for 1000±48 hours in an atmosphere of 90~95%RH at istic change shall meet the following requirement.</li> <li>Performance</li> <li>Within ±20% of initial capacitance</li> <li>Less than or equal to 1.5 times of the value of item</li> </ul>
	5	tan δ	4.4
4.9	Damp heat	ESR	Less than or equal to 1.5 times of the value of item 4.5
	test	Leakage current	Less than or equal to the value of item 4.3
		Appearance	Notable changes shall not be found.
I			

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				_					
4.10	Maximum permissible (ripple current)	The At 1 Tabl The rated Freq	100kHz and c ole 3	can be alue o d shal	e applied at r of D.C voltag ill not reverse	current is the m maximum opera ge and the peak e voltage. $1 \text{kHz} \leq 1 \text{f} < 10 \text{kHz} \\ 0.30$	rating tempera	shall not shall not z f<5	exceed the 0kHz≤ 500kHz 1.00
4.11	Rapid change of temperature	Cycle Test c Perfo	ied voltage: v e number: 5 c diagram: Fig. ormance: The Item pacitance cha tan δ	cycles g.1 e capa	s acitors shall r Performand Within ±1	← 1cycl	R $30 \pm 3 \text{ min}$ $30 \pm 3 \text{ min}$ 1  or less 1  or less 1  or less 1  or less 1  or less		erature
		Le	eakage curren	nt		or equal to the v			
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a) Lead pull strength A static load force shall be applied to the terminal in the axial direction in a direction away from the body for $10 \pm 1$ s.	and acting						
	and acting						
in a direction away from the body for $10 \pm 1$ s.	and deting						
	- I						
Lead wire diameter (mm) Load force (N)	4						
$0.5 < d \le 0.8$							
<ul> <li>4.12 Lead strength</li> <li>b) Lead bending When the capacitor is placed in a vertical position and the weight specing table above is applied to one lead and then the capacitor is slowly rotated horizontal position and then returned to a vertical position thus complete for 2~3 seconds. The additional hands are made in the appreciate direction</li> </ul>	$ed 90^{\circ}$ to a						
The additional bends are made in the opposite direction							
Lead wire diameter (mm) Load force (N)							
$0.5 < d \le 0.8$							
Performance: The characteristic shall meet the following value after a)	or b) test.						
Item Performance							
Leakage current Less than or equal to the value of item4.	3						
Outward Appearance No cutting and slack of lead terminals							
4.13 Resistance to vibration $F_{x, y, z}$ (3 axes) Duration: 2hours/ axial (Total 6 hours) The capacitors are supported as the following Fig2 $\leq 0.3$ mm Fig2 Performance: Capacitance value shall not show drastic change compared to capacitance when the value is measured within 30 minutes. Prior to the com	Duration: 2hours/ axial (Total 6 hours) The capacitors are supported as the following Fig2 $\leq 0.3$ mm Fig2						
exam, Capacitance difference shall be within $\pm 5\%$ compared to the initial vexam.	-						
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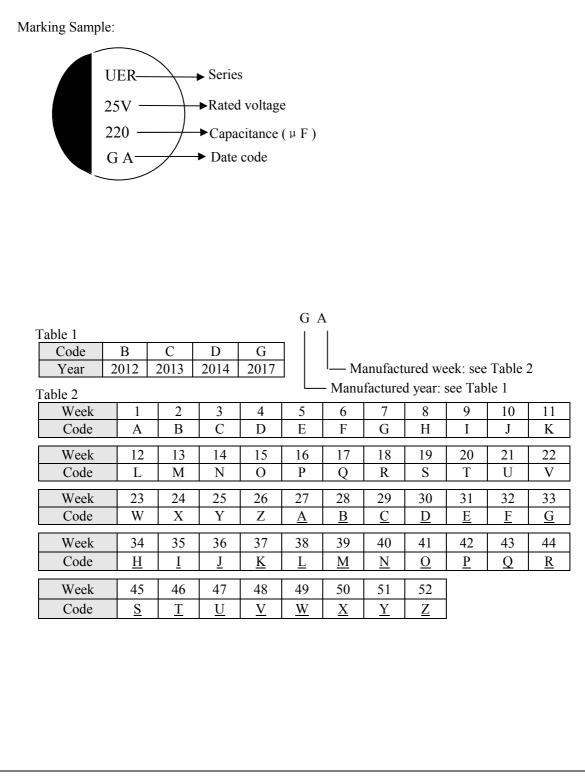


4.14	Solderability	The capacitor shall be tested under the following conditions:Solder: Sn-3Ag-0.5CuSoldering temperature: 245±3°CImmersing time: 3±0.5sImmersing depth: 1.5~ 2.0mm from the root.Flux: Approx .25% rosinPerformance: At least 95% of the dipped portion of the terminal shall be covered with new solder.
		<ul> <li>A) Solder bath method Lead terminals of a capacitor are placed on the heat isolation board with thickness of 1.6±0.5mm. It will dip into the flux of isopropylaehol solution of colophony.</li> <li>Then it will be immersed at the surface of the solder with the following condition: Solder : Sn-3Ag-0.5Cu Soldering temperature : 260 ±5°C Immersing time : 10±1s Heat protector: t=1.6mm glass –epoxy board</li> <li>B) Soldering iron method Bit temperature : 400 ±10°C Application time : 3+1/-0 s Heat protector: t=1.6mm glass –epoxy board</li> <li>For both methods, after the capacitor at thermal stability, the following items shall be</li> </ul>
4.15		measured:ItemPerformanceCapacitance ChangeWithin $\pm 5\%$ of initial capacitancetan $\delta$ Less than or equal to the value of item 4.4ESRLess than or equal to the value of item 4.5Leakage currentLess than or equal to the value of item 4.3 (after voltage treatment)AppearanceNotable changes shall not be found.

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### 5. Product Marking



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#### 6. Product Dimensions, Impedance & Maximum Permissible Ripple Current Unit: mm $\phi d \pm 0.05$ F±0.5 L<sup>+1.5</sup> -1.0 15 min 4 min $\Phi$ D $\pm$ 0.5 8 φD $\mathbf{L}$ 11.5 F 3.5 φd 0.6 Table 3 ESR Leakage Working Dimension Maximum permissible Capacitance current at 20°C100kHz Voltage $(D \times L,$ ripple current at 105℃ (µA) (µF) to300kHz (V)mm) 100kHz (mA rms) 2min $(m\Omega)$ 25 220 8X11.5 3000 28 1100

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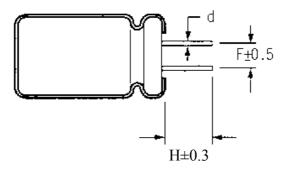
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### 7. Forming Dimension

### Unit: mm

Shape Code	φD	Φ8
	F	3.5
СВ	Н	3.3
	d	0.6

СВ Туре



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### 7.Application Guideline:

X-CON Solid Aluminum Electrolytic Capacitor should be used compliance with the following guidelines

- 7-1Circuit design
  - Prohibited Circuits for use

Do not use the capacitors with the following circuits.

- 1) Time constant circuits
- 2) Coupling circuits
- 3) Circuits which are greatly affected by leakage current
- 4) High impedance voltage retention circuits.
- 7-2. Voltage
  - 1) Over voltage

The application of over-voltage and reverse voltage below can cause increases in leakage current and short circuits. Applied voltage, refers to the voltage value including the peak value of the transitional instantaneous voltage and the peak Value of ripple voltage, not just steady line voltage. Design your circuit so that the peak voltage does not exceed the stipulated voltage.

Over voltage exceeding the rated voltage may not be applied even for an instant as it may cause a short circuit.

2) Applied voltage

① Sum of the DC voltage value and the ripple voltage peak values must not exceed the rated voltage.

(2) When DC voltage is low, negative ripple voltage peak value must not become a reverse voltage that exceeds 10% of The rated voltage.

③ Use the X-CON within 20% of the rated voltage for applications which may cause the reverse voltage during the Transient phenomena when the power is tumid off or the source is switched.

7-3 Sudden charge and discharge restricted

Sudden charge and discharge may result in short circuit's large leakage current. Therefore, a protection circuits are recommended to design in when on of the following condition is expected.

1) The rush current exceeds 10A

2) The rush current exceeds 10 times of allowable ripple current of X-CON.

A protection resistor (1K  $\Omega$ ) must be inserted to the circuit during the charge and discharge when measuring the leakage Current.

7-4 Ripple current

Use the capacitors within the stipulated permitted ripple current. When excessive ripple current is applied to the capacitor, It causes increases in leakage current and short circuits due to self- heating. Even when using the capacitor under the Permissible ripple current, reverse voltage may occur if the DC bias voltage is low.

7-5 Leakage current

There is a risk of leakage current characteristics increasing even if the following use environments are within the stipulated range However, even if leakage current increases once, it has the characteristic that leakage current becomes small in most cases after voltage is applied due to its self-correction mechanism.

7-6 Failure rate

The main failure mode of X-CON is open mode primarily caused by electrostatic capacity drop at high temperature (i.e.wear out failure), besides random short circuit mode failures primarily caused by over voltage occurs as minor one. The time it takes to reach the failures mode can be extended by using the X-CON with reduced ambient temperature, ripple current and applied voltage.

7-7 Capacitor insulation

1) Insulation in the marking sleeve is not guaranteed. Be aware that the space between the case and the negative electrode Terminal is not insulated and has some resistance.

2) Be sure to completely separate the case, negative lead terminal, and positive lead terminal and PCB patterns with each other.

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#### 7-8 Precautions for using capacitors

X-CON capacitors should not be used in the following environments.

1) Environments where the capacitor is subject to direct contact with salt water or oil can directly fall on it.

2) Environments where capacitors are exposed to direct sunlight.

3) High temperature (Avoid locating heat generating components around the X-CON and on the underside of the

PCB), or humid environments where condensation can form on the surface of the capacitor.

4) Environments where the capacitor is in contact with chemically active gases.

5) Acid or alkaline environments.

6) Environment subject to high-frequency induction.

7) Environment subject to excessive vibration and shock.

#### 8. Mounting Precautions

touch X-CON.       2) Washing the PCB (available       Used immersion or ultrasonic waves to clean for a total or	Mounting phase	Things to note before mounting	Disposal
Before mounting         after long storage         resistance for 1 hour at the range between 60 and 70°C           3) X-CON capacitors dropped to the floor         Not reused           4) Precautions on polar, capacitance and rated voltage         Products without remarkable polar, capacitance and rated voltage           5) Precautions on the pitch between lead terminal and PCB         The products can be used only when said pitch is matched terminal and body of X-CON capacitors enduring in mounting           6) Precautions on the stress that lead terminal and body of X-CON capacitors enduring in mounting         The products can be used for production only when lead terminal and body of X-CON capacitors enduring in mounting           1) Soldering with a soldering iron         Both temperature and duration in mounting; Don't let the tip of the soldering iron touch the X-CON itself.           Mounting         2) Flow soldering         X-CON capacitor body should be prohibited to submerger in melted solder; both temperature and duration in mounting; SPEC; The rosin is not allowed to adhere to any where other than lead terminal.           1) Precautions on mounting status         Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.           2) Washing the PCB (available cleaning agent 1) high quality alcohol-based cleaning fluid such as st-100s, 750L,750M;2) Detergents including substitute freon such as         Used immersion or ultrasonic waves to clean for a total o less than 5 minutes and the temperature be less than 60°C		1) Used X-CON capacitors	Not reused
Before mounting       3) X-CON capacitors dropped to the floor       Not reused         4) Precautions on polar, capacitance and rated voltage       Products without remarkable polar, capacitance and rated voltage shouldn't be available         5) Precautions on the pitch between lead terminal and PCB       The products can be used only when said pitch is matched terminal and body of X-CON capacitors enduring in mounting         1) Soldering with a soldering iron       Both temperature and duration in mounting should meet the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the soldering iron touch the X-CON itself.         Mounting       2) Flow soldering       X-CON capacitor body should be prohibited to submerge in melted solder; both temperature and duration in mounting SPEC; The rosin is not allowed to adhere to any where other than lead terminal.         1) Precautions on mounting status       Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.         2) Washing the PCB (available cleaning fluid such as st-100s, 750L;750M;2) Detergents including substitute freon such as the maximum operating temperature).       Used immersion or ultrasonic waves to clean for a total o less than 5 minutes and the temperature.		2) LC-increased X-CON capacitors	Apply them with rated voltage in series with 1K $\Omega$
Before mounting       Image: the form of the product of the products without remarkable polar, capacitance and rated voltage       Products without remarkable polar, capacitance and rated voltage shouldn't be available         5)       Precautions on the pitch between lead terminal and PCB       The products can be used only when said pitch is matched terminal and body of X-CON capacitors enduring in mounting         6)       Precautions on the stress that lead terminal and body of X-CON capacitors enduring in mounting       The products can be used for production only when lead terminal and body of X-CON capacitors enduring in mounting         Mounting       1)       Soldering with a soldering iron       Both temperature and duration in mounting should meet the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the soldering iron touch the X-CON itself.         Mounting       2)       Flow soldering       X-CON capacitor body should be prohibited to submergy in melted solder; both temperature and duration in mounting should meet the requirements of out-going SPEC; The rosin is not allowed to adhere to any where other than lead terminal.         1)       Precautions on mounting status       Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.         2)       Washing the PCB (available cleaning agent 1) high quality alcohol-based cleaning fluid such as st-100s, 750L,750M;2) Detergents including substitute freon such as       Used immersion or ultrasonic waves to clean for a total o less than 5 minutes and the temperature be less than 60°C		after long storage	resistance for 1 hour at the range between 60 and $70^{\circ}$ C
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Betote mounting         and rated voltage         voltage shouldn't be available           5) Precautions on the pitch between lead terminal and PCB         The products can be used only when said pitch is matched terminal and body of X-CON capacitors enduring in mounting         The products can be used for production only when lead terminal and body of X-CON capacitors enduring in mounting           1) Soldering with a soldering iron         Both temperature and duration in mounting should meet the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the soldering iron touch the X-CON itself.           2) Flow soldering         X-CON capacitor body should be prohibited to submergy in melted solder; both temperature and duration in mounting should meet the requirements of out-going SPEC; The rosin is not allowed to adhere to any where other than lead terminal.           1) Precautions on mounting status         Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.           2) Washing the PCB (available cleaning agent 1)high quality alcohol-based cleaning fluid such as st-100s, 750L,750M;2) Detergents including substitute freon such as         Used immersion or ultrasonic waves to clean for a total o less than 5 minutes and the temperature be less than 60°C The conductivity, PH, specific gravity and water cleaning X-CON products should be dried with hot air (less than the maximum operating temperature).		floor	
After mounting         1) Precautions on mounting status         X-CON capacitor body should meet the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the soldering iron touch the X-CON itself.           Mounting         2) Flow soldering         X-CON capacitor body should meet the requirements of out-going SPEC; The rosin is not allowed to adhere to any where other than lead terminal.           I) Precautions on mounting status         Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.           2) Washing the PCB (available cleaning agent 1) high quality alcohol-based cleaning fluid such as st-100s, 750L,750M;2) Detergents including substitute freon such as         Used immersion or ultrasonic waves to clean for a total of the maximum operating temperature).	Before mounting	4) Precautions on polar, capacitance	
Image: Instant of the image: Instan	Defore mounting		-
6) Precautions on the stress that lead terminal and body of X-CON capacitors enduring in mounting       The products can be used for production only when lead terminal and body are not subject stress.         1) Soldering with a soldering iron       Both temperature and duration in mounting should meet the requirements of out-going SPEC; no stress should be allowed to occur in mounting; Don't let the tip of the soldering iron touch the X-CON itself.         Mounting       2) Flow soldering       X-CON capacitor body should be prohibited to submerge in melted solder; both temperature and duration in mounting should meet the requirements of out-going SPEC; The rosin is not allowed to adhere to any where other than lead terminal.         Precautions on mounting status       Do not tilt, bend twists X-CON; Do not allow other matte touch X-CON.         After mounting       2) Washing the PCB (available cleaning agent 1)high quality alcohol-based cleaning fluid such as st-100s v 750L,750M;2) Detergents including substitute freon such as       Used immersion or ultrasonic waves to clean for a total o less than 5 minutes and the temperature be less than 60°C			The products can be used only when said pitch is matched
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		AK-225AES and IPA)	

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# 9.It refers to the latest document of "Environment-related Substances standard"(WI-HSPM-QA-072).

	Substances					
	Cadmium and cadmium compounds					
Heavy metals	Lead and lead compounds					
Ticavy metals	Mercury and mercury compounds					
	Hexavalent chromium compounds					
	Polychlorinated biphenyls (PCB)					
Chloinated	Chloinated Polychlorinated naphthalenes (PCN)					
organic	Polychlorinated terphenyls (PCT)					
compounds	Short-chain chlorinated paraffins(SCCP)					
	Other chlorinated organic compounds					
Duraninatal	Polybrominated biphenyls (PBB)					
Brominated	Polybrominated diphenylethers(PBDE) (including					
organic	decabromodiphenyl ether[DecaBDE])					
compounds	Other brominated organic compounds					
Tributyltin comp	ounds(TBT)					
Triphenyltin con	npounds(TPT)					
Asbestos						
Specific azo com	ipounds					
Formaldehyde						
Polyvinyl chloric	de (PVC) and PVC blevds					
Beryllium oxide						
Beryllium copper						
Specific phthalat	es (DEHP,DBP,BBP,DINP,DIDP,DNOP,DNHP)					
Hydrofluorocarb	on (HFC), Perfluorocarbon (PFC)					
Perfluorooctane	sulfonates (PFOS)					
Specific Benzotr	iazole					

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